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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/880,223	06/13/2001	Louis L. Hsu	728-208(YOR9-2001-0270 5309 US	
7590 07/28/2004		EXAMINER		
Paul J. Farrell, Esq. DILWORTH & BARRESE LLP 333 Earle Ovington Boulevard Uniondale, NY 11553			RAO, SHRINIVAS H	
			ART UNIT	PAPER NUMBER
			2814	
			DATE MAILED: 07/28/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)			
Office Action Summary		09/880,223	HSU ET AL.			
		Examiner	Art Unit			
	···	Steven H. Rao	2814			
	The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply					
THE - External after - If the control of the contro	ORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION. Insions of time may be available under the provisions of 37 CFR 1.1 SIX (6) MONTHS from the mailing date of this communication. It period for reply specified above is less than thirty (30) days, a reply of period for reply is specified above, the maximum statutory period were to reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).			
Status						
1)⊠	1) Responsive to communication(s) filed on 13 May 2004.					
2a)⊠		action is non-final.				
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Dispositi	on of Claims					
 4) Claim(s) 12 and 14-17 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) is/are allowed. 6) Claim(s) 12 and 14-17 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement. 						
Applicati	on Papers					
9) The specification is objected to by the Examiner.						
10)[10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.					
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
11)[Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.					
Priority ι	ınder 35 U.S.C. § 119					
a)	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority documents application from the International Bureausee the attached detailed Office action for a list	s have been received. s have been received in Application rity documents have been received u (PCT Rule 17.2(a)).	on No ed in this National Stage			
Attachment(s)						
· <u> </u>	e of References Cited (PTO-892)	4) Interview Summary Paper No(s)/Mail Da	•			
3) 🔲 Infor	e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date		atent Application (PTO-152)			

Response to Amendment

Applicants' amendment filed on May 17, 2004 has been entered on May 23, 2004.

Therefore claim 12 as amended by the amendment and The examiner's amendment below and claims 14-17 as previously filed are currently pending.

Claims 1-11,13 and 18 -31 were previously cancelled.

Examiner's Amendment

During a telephone interview with Jeffery Kirshner on Thrusday July 15, 2004, Mr. Krishner authorized Ex. Rao to delete, "formed in a polysilicon layer "in line 5 of claim 12.

It is noted that "formed in a polysilicon layer" was suggested as alternative language if supported by the specification to attempt to overcome the 112 rejections.

It is noted that Applicants' specification apge 7 lines

Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claims 12, 14 1-7 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

Claim 12 recites, "wherein said transfer gate covers the entire top surface of said thyristor" is not supported by the specification as originally filed.

The written description does not contain disclosure that the horizontally stacked pseudo-TFT transfer gate as covering the entire top surface of the PNP thyristor 212.

The drawing figures do not show the horizontally stacked pseudo-TFT transfer gate (identified as numeral 220 in Figure 13) as covering the entire top surface of the PNP thyristor 212, rather the drawings show a gap between WLL2 and the end of the horizontally stacked pseudo-TFT transfer gate above region 120 C in figure 13.

The previous rejection also contained this rejection and specifically stated that the previous rejection was based on the assumption arguendo

"Assuming arguendo that the newly added limitation," wherein said thyristor being buried underneath said transfer gate, wherein said transfer gate covers the entire top surface of said first device, and further wherein the top surface of said transfer gate forms a planar top surface of each said transfer gate of each of said T-Ram cell." is supported by the specification as originally filed the following rejection is made."

Applicants' reference to figure 13 in their remarks section is inadequate to overcome the rejection and does not provide any support in the original specification to show that the horizontally stacked pseudo-TFT transfer gate (identified as numeral 220 in Figure 13) as covering the entire top surface of the PNP thyristor 212.

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The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 12 and 14-17 are rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Patent No. 6,448,586 to Nemati et al. (herein after Nemati) in view of Kumagi (U.S. Patent .No. 5,357,125 herein after Kumagi) both previously applied . For response to Applicants' arguments see section below.

With respect to claim 12, a T-Ram array including a plurality of T-Ram cells arranged in an array (Nemati fig. 8, col. 6 lines 65-66), wherein each of the plurality of T-Ram cells includes a buried vertical thyristor region beneath at least a portion of a transfer gate region. (Nemati fig.8, p portion of 40 a, b, and c under respective gate 48).

Nemati does not label his gate as a transfer gate however it is inherent from the description in col. 7 lines 1-15 that Nemati's gate 48 functions like a pseudo TFT (similar to applicant's description at page 5 of the specification) and therefore one of ordinary skill in the art would readily recognize Nemati's gate 48 to be a transfer gate similar to that claimed.

The remaining limitations of claim 12 are:

And a horizontally stacked pseudo-TFT transfer gate, (see above), said transfer gate (i.e. pseudo TFT) including a source/drain and body (Nemati col. 5 lines 46 to 61).

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Assuming arguendo that the newly added limitation, "wherein said thyristor being buried underneath said transfer gate, wherein said transfer gate covers the entire top surface of said first device, and further wherein the top surface of said transfer gate forms a planar top surface of each said transfer gate of each of said T-Ram cell." is supported by the specification as originally filed the following rejection is made.

Nemati does not specifically describe the newly added limitation wherein said second device being buried underneath said second device, wherein said second device covers the entire top surface of said first device, and further wherein the top surface of said transfer gate forms a planar top surface of each said transfer gate of each of said T-Ram cell.

However, Kumagi in figures 1-5 and col. 5 lines 61-68 and figures 2 and 5 describes wherein said second device being buried underneath said second device, wherein said transfer gate covers the entire top surface of said thyristor, and further wherein the top surface of the transfer gate forms a co-planar top surface of each said transfer gate of each of said T-Ram cell to form a semiconductor device that is readily integrated into one chip and can be effectively used as a power switching device.

Therefore it would have been obvious to one of ordinary skill in the art to include Kumagi's said thyristor buried underneath said transfer gate, wherein said transfer gate covers the entire top surface of said thyristor, and further wherein the top surface of the transfer gate forms a co-planar top surface of each said transfer gate of each of said T-Ram cell and wherein Nemati's device to form a semiconductor device that is

readily integrated into one chip and can be effectively used as a power switching device.

With respect to claim 14, wherein each of the plurality of cells has a size less than or equal to 8 F². (It is well known in the prior art that T-ram cells have a size of 8F² or less as admitted by the applicants' herein in their co-pending application No.2002/0093030 published on July 18, 2002 in its abstract lines 10 –13 etc.)

With respect to claim 15, wherein said substrate is a semiconductor SOI or bulk wafer (Neamti fig. 6a # col. 6 lines 20-27).

With respect to claim 16, wherein the base of said thyristor is surrounded by a surround gate. (Nemati fig. 8 thyristors 40 a, b and c being surrounded by the gate 48).

With respect to claim 17, Nemati describes wherein each of the plurality of T-Ram cells includes structure for the traversal of at least two word lines there through. (Nemati fig. 5, col. 5 lines 33-60) said planar top surface of each T-Ram cell provides for simplified fabrication of metal wirings, said wirings being fabricated over said planar top surface of said T-Ram cells, said wirings for inter connecting said T-Ram cells.

The limitation, "said planar top surface of each T-Ram cell provides for fabrication of metal wirings, said wirings being fabricated over said planar top surface of said T-Ram cells, said wirings for inter connecting said T-Ram cells " is taken to be a product by process limitation.

Response to Arguments

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Applicant's arguments filed 5/17/ 2004 have been fully considered but they are not persuasive for the following reasons:

Applicants' first contention that Nemati does not disclose a stacked pseudo-TFT transfer gate but rather discloses a control gate (i.e. #48) is not persuasive because Nemati as previously stated in figure 6 and col. 5 lines 61 –65 states its element 48 is a stacked psuedo TFT.

FIG. 6 illustrates an alternative implementation to that which is shown in FIG. 1. The structures of FIGS. 1 and 6 differ in that the structure of FIG. 6 includes a vertically-arranged NMOSFET 30 instead of the NMOSFET 12 of 65 FIG. 1, which is arranged in a planar manner relative to the P substrate. The NMOSFET 30 includes a gate 14' that at

Applicants' arguments of 8/11/2003 namely, "In contrast, it is inherent in a pseudo_TFT gate as recited in claim 12 as amended that both the source/ drain and the body are contained in a polysilicon layer. "was not purasive because the same was not recited in the claim 12 till applicants' amendment of 1/23/2004, and therefore Applicants' arguments were not consumerate in scope with their arguments.

Applicants' amendment of 1/23/2004 again has 112 problems because claim1 2 presently recites "said transfer gate including a source/drain and body formed in a polysilcion layer ". It is understood by one skilled in the art that a gate does not include a source/drain and body regions, but that a pseudo-TFT may include the source/drain and body regions, assuming this is what Applicants' meant, all the added limitations are taught by Nemati col. 5 lines 46 to 61.

Dependent claims 14-16 and (17) were alleged to be allowable as they depend upon allegedly allowable claim 12.

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However as shown above claim 12 is not allowable. Therefore claims 14-17 as also not allowable.

Any inquiry concerning this communication or earlier communication from the examiner should be directed to Steven H. Rao whose telephone number is (571) 272-1718. The examiner can normally be reached on Monday- Friday from approximately 8:00 a.m. to 5:30 p.m.

Any inquiry of a general nature or relating to the status of this application should be directed to the Group receptionist whose telephone number is (703) 308-0956. The Group facsimile number is (703) 308-7724.

Steven H. Rao

Patent Examiner

July 21, 2004.

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